

2.0x1.25mm INFRARED EMITTING DIODE

Part Number: KP-2012SF4C

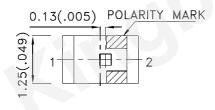
Features

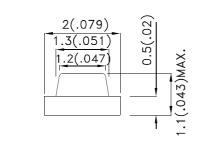
- 2.0mmx1.25mm SMT LED,1.1mm thickness.
- Mechanically and spectrally matched to the phototransistor.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

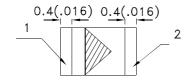
Description

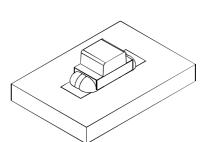
SF4 Made with Gallium Aluminum Arsenide Infrared Emitting diodes.

Package Dimensions









- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1(0.004")$ unless otherwise noted.
- The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.

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Selection Guide

Part No.	Dice	Lens Type	Po (mW/sr) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
KP-2012SF4C	SF4 (GaAlAs)	Water Clear	0.8	1.5	120°

Notes:

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Radiant Intensity/ luminous flux: +/-15%.
- 3. Radiant Intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Parameter	P/N	Symbol	Тур.	Max.	Units	Test Conditions	
Forward Voltage [1]	SF4	VF	1.3	1.6	٧	IF=20mA	
Reverse Current	SF4	lR		10	uA	VR = 5V	
Capacitance	SF4	С	90		pF	VF=0V;f=1MHz	
Peak Spectral Wavelength	SF4	λР	880		nm	IF=20mA	
Spectral Bandwidth	SF4	Δλ1/2	50		nm	IF=20mA	

1. Forward Voltage: +/-0.1V.

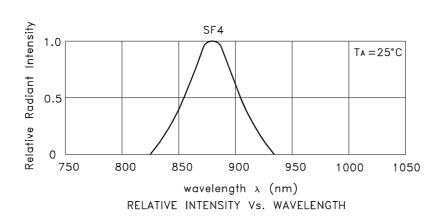
2. Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

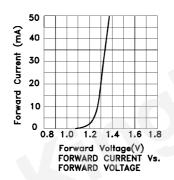
Parameter	Symbol	SF4	Units
Power dissipation	PD	80	mW
DC Forward Current	lF	50	mA
Peak Forward Current [1]	iFS	1.2	А
Reverse Voltage	VR	5	V
Operating Temperature	Та	-40 To +85	°C
Storage Temperature	Тѕтс	-40 To +85	°C

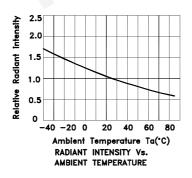
Note: 1. 1/100 Duty Cycle, 10µs Pulse Width.

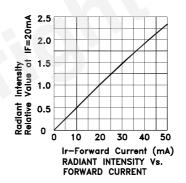
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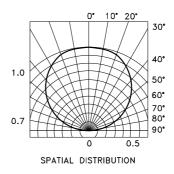


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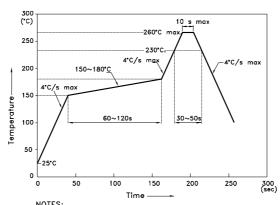
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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



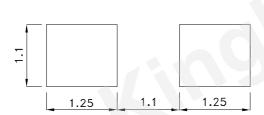
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.

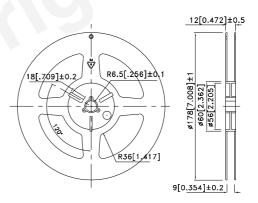
 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
- to high temperature.

 3.Number of reflow process shall be 2 times or less.

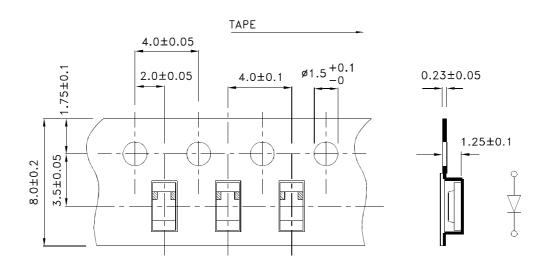
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Reel Dimension



Tape Specifications (Units: mm)

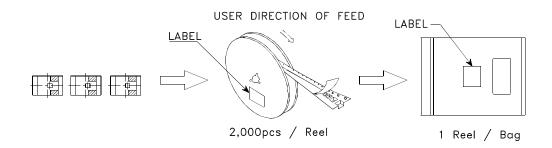


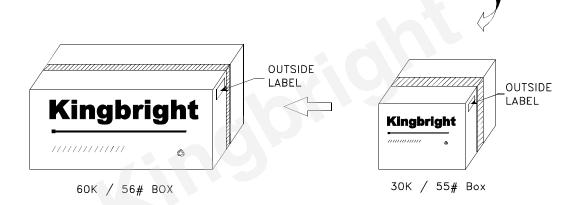
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PACKING & LABEL SPECIFICATIONS

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Detailed application notes are listed on our website. http://www.kingbright.com/application_notes

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